

Silicon Carbide (SiC) MOSFET - 60 mohm, 900 V, M2, TO-247-3L

NVHL060N090SC1

Features

- Typ. $R_{DS(on)} = 60 \text{ m}\Omega$ @ $V_{GS} = 15 \text{ V}$
- Typ. $R_{DS(on)} = 43 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge (typ. $Q_{G(tot)} = 87 \text{ nC}$)
- Low Effective Output Capacitance (typ. Coss = 113 pF)
- 100% UIL Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

Typical Applications

- Automotive On Board Charger
- Automotive DC-DC converter for EV/HEV

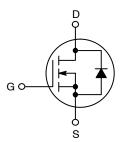
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	900	V
Gate-to-Source Voltage			V _{GS}	+22/-8	V
Recommended Operation Values of Gate-to-Source Voltage	T _C < 175°C		V_{GSop}	+15/-5	٧
Continuous Drain Current R _{0JC}	Steady State $T_C = 25^{\circ}C$		I _D	46	Α
Power Dissipation $R_{\theta JC}$			P_{D}	221	V
Continuous Drain Current R _{0JC}	Steady State T _C = 100°C		Ι _D	32	Α
Power Dissipation $R_{\theta JC}$			P_{D}	110	W
Pulsed Drain Current (Note 2)	T _A = 25°C		I _{DM}	184	Α
Single Pulse Surge Drain Current Capability (Note 3)	T_A = 25°C, t_p = 10 μ s, R_G = 4.7 Ω		I _{DSC}	320	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			Is	22	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 18 A, L = 1 mH) (Note 4)			E _{AS}	162	mJ

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

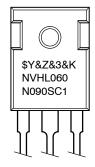
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX
900 V	84 mΩ @ 15 V	46 A

N-CHANNEL MOSFET





MARKING DIAGRAM



\$Y = onsemi Logo &Z = Assembly Plant Code &3 = Data Code (Year & Week) &K = Lot

NVHL060N090SC1 = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
NVHL060N090SC1	TO247-3L	30 Units / Tube

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Note 1)	$R_{\theta JC}$	0.68	°C/W
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	40	°C/W

- 1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

 2. Repetitive rating, limited by max junction temperature.

- Peak current might be limited by transconductance.
 E_{AS} of 162 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 18 A, V_{DD} = 100 V, V_{GS} = 15 V.

ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	900			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 1 mA, referenced to 25°C		574		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V}, V_{DS} = 900 \text{ V}, T_{J} = 25^{\circ}\text{C}$			100	μΑ
		V _{GS} = 0 V, V _{DS} = 900 V, T _J = 175°C			250	
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +22/-8 V, V _{DS} = 0 V			±1	μΑ
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}$, $I_D = 5 \text{ mA}$	1.8	2.7	4.3	V
Recommended Gate Voltage	V _{GOP}		-5		+15	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D = 20 A, T _J = 25°C		60	84	mΩ
		V _{GS} = 18 V, I _D = 20 A, T _J = 25°C		43		
		V _{GS} = 15 V, I _D = 20 A, T _J = 175°C		76	135	
Forward Transconductance	9FS	V _{DS} = 20 V, I _D = 20 A		17		S
CHARGES, CAPACITANCES & GATE	RESISTANCE			•		
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 450 V		1770		pF
Output Capacitance	Coss			113		
Reverse Transfer Capacitance	C _{RSS}			11		
Total Gate Charge	Q _{G(tot)}	$V_{GS} = -5/15 \text{ V}, V_{DS} = 720 \text{ V}, I_D = 10 \text{ A}$		87		nC
Threshold Gate Charge	Q _{G(th)}			17		
Gate-to-Source Charge	Q _{GS}			27		
Gate-to-Drain Charge	Q_{GD}	1		26		
Gate Resistance	R _G	f = 1 MHz		3.0		Ω
SWITCHING CHARACTERISTICS				1		1
Turn-On Delay Time	t _{d(on)}	$V_{GS} = -5/15 \text{ V}, V_{DS} = 720 \text{ V},$		22	40	ns
Rise Time	t _r	I_D = 20 A, R_G = 2.5 Ω, Inductive Load		33	66	1
Turn-Off Delay Time	t _{d(off)}	maddive Edad		31	74	1
Fall Time	t _f	1		11	20	1
Turn-On Switching Loss	E _{ON}	1		464		μJ
Turn-Off Switching Loss	E _{OFF}	1		23		1
Total Switching Loss	E _{TOT}	1		487		1
DRAIN-SOURCE DIODE CHARACTER		1	<u> </u>	1	<u> </u>	II.
Continuous Drain-to-Source Diode Forward Current	I _{SD}	V _{GS} = -5 V, T _J = 25°C			22	А
Pulsed Drain-to-Source Diode Forward Current (Note 2)	I _{SDM}	$V_{GS} = -5 \text{ V}, T_{J} = 25^{\circ}\text{C}$			184	А
Forward Diode Voltage	V _{SD}	V _{GS} = -5 V, I _{SD} = 10 A, T _J = 25°C		3.9		V

ELECTRICAL CHARACTERISTICS (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
DRAIN-SOURCE DIODE CHARACTE	RISTICS		•			
Reverse Recovery Time	t _{RR}	$V_{GS} = -5/15 \text{ V}, I_{SD} = 30 \text{ A},$ $dI_{S}/dt = 1000 \text{ A}/\mu\text{s}, V_{DS} = 720 \text{ V}$		18		ns
Reverse Recovery Charge	Q _{RR}			84		nC
Reverse Recovery Energy	E _{REC}			1.0		μJ
Peak Reverse Recovery Current	I _{RRM}			9.0		Α
Charge Time	ta			10		ns
Discharge Time	t _b]		8.0		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

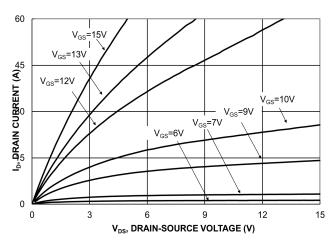


Figure 1. On-Region Characteristics

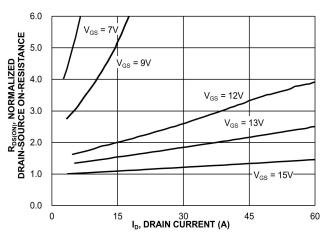


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

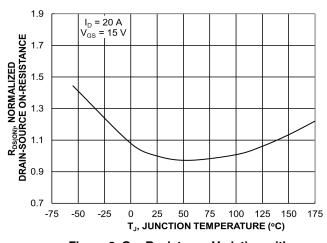


Figure 3. On–Resistance Variation with Temperature

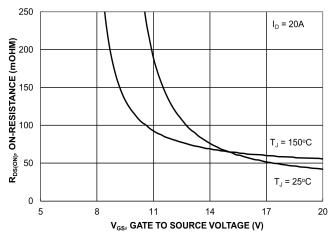


Figure 4. On-Resistance vs. Gate-to-Source Voltage

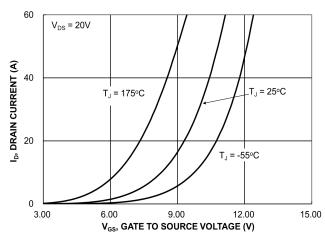


Figure 5. Transfer Characteristics

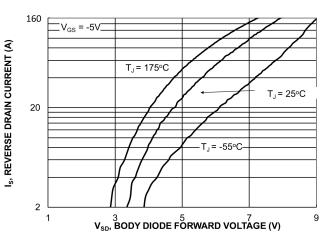


Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS (continued)

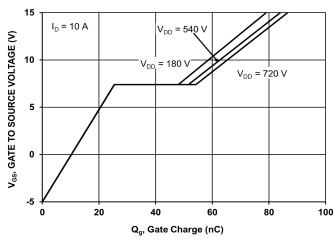


Figure 7. Gate-to-Source Voltage vs. Total Charge

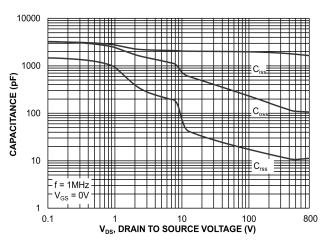


Figure 8. Capacitance vs. Drain-to-Source Voltage

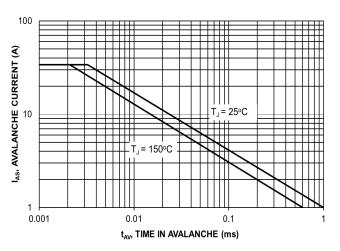


Figure 9. Unclamped Inductive Switching Capability

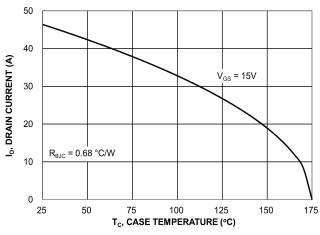


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

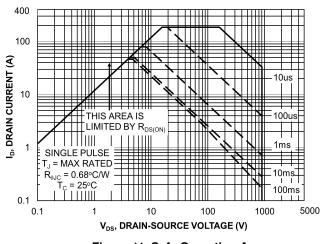


Figure 11. Safe Operating Area

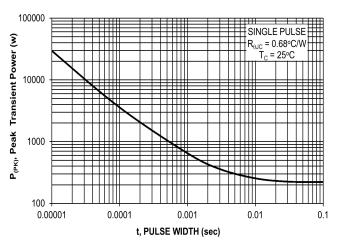


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

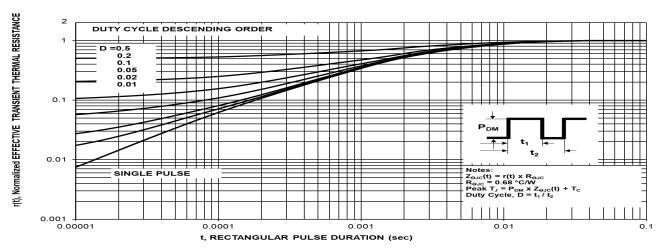
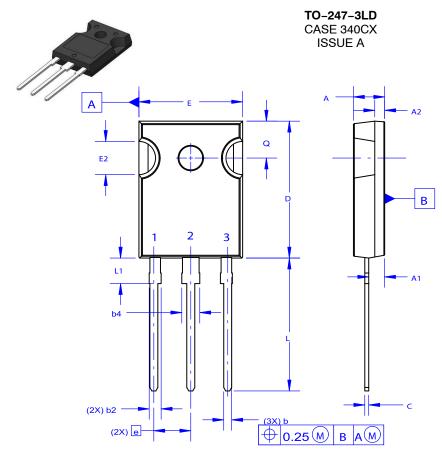


Figure 13. Junction-to-Ambient Thermal Response

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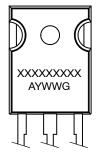




NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

Ø _P —		Φ _{P1} D2
E1 —	2	D1
		I

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

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